NEXT ASSY	USED ON	REVISIONS			
		REV.	DESCRIPTION	DATE	APPR.
		—	RELEASED DCR 100142	10-11-77	—

The following modifications are required to incorporate SM1+ & WAIT+ Options to the CPU Board up to Revision D.

Modification for SM1+

1. Cut Trace from IC17-3 to IC16-7 on front of board. Sheet 2.
2. Cut trace from IC8-5 to P1-97.
3. Jumper IC17-3 to IC14-4. Sheet 4.
4. Jumper IC8-5 to P1-44. Sheet 4, 5.

   The following steps must be made to complete this Jumper.

   A. Solder to IC8-5 using #28 AWG insulated wire. Feed wire thru Feedthru hole as shown on sheet 3. Solder other end to P1-44 on component side of Board. Note: Solder to no more than the top (away from edge of card) 1/16" of the gold Tab. Gold provides an excellent surface for solder flow when hot. You must be very careful not to heat the gold Tab more than necessary or solder will coat the entire Tab (solder cannot be removed from the gold surface). Sheet 5.

Modification for WAIT+

5. Jumper IC14-24 to IC8-3. Sheet 4.
6. Jumper IC8-2 to P1-27. Sheet 4.

Notes: SWO is eliminated by this modification.

This mod. retains HLTA and INTA for use w/Extensys memory cards.

N. P. Sanchez	DATE 10-11-77	PolyMorphic Systems 460 Ward Drive Santa Barbara Ca 93111 (805) 967-2351
CK		
R. JHA	10-11-77	MODIFICATION -#2 SM1 & WAIT +

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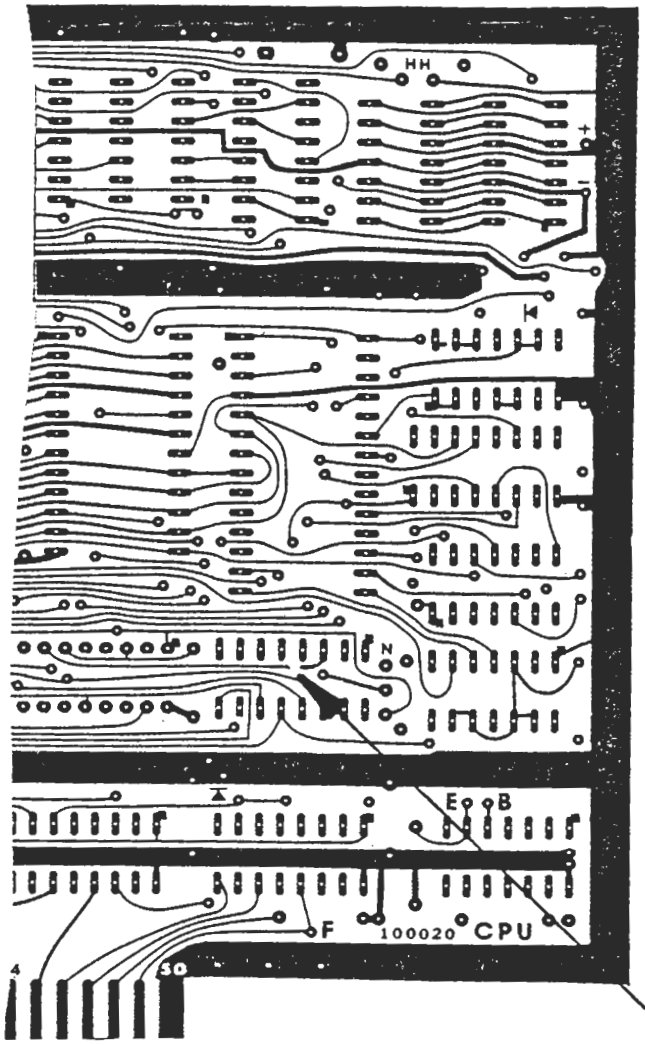
SIZE		DRAWING NUMBER	REV
A	SHEET 1 OF 5	104433	



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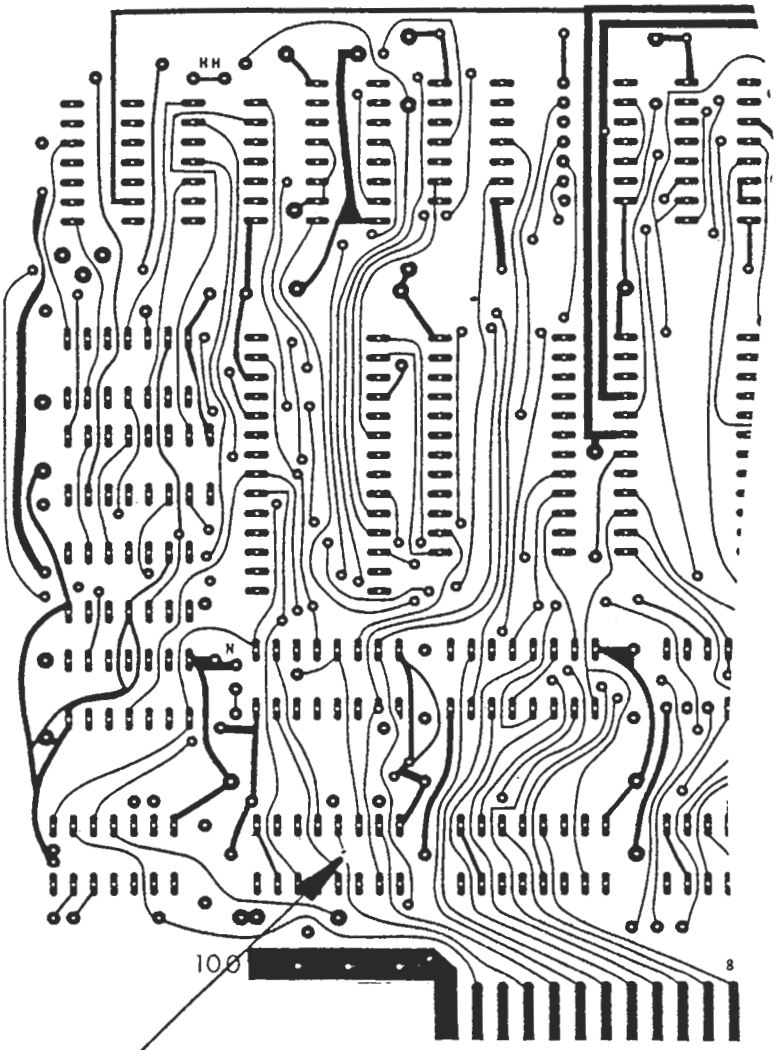

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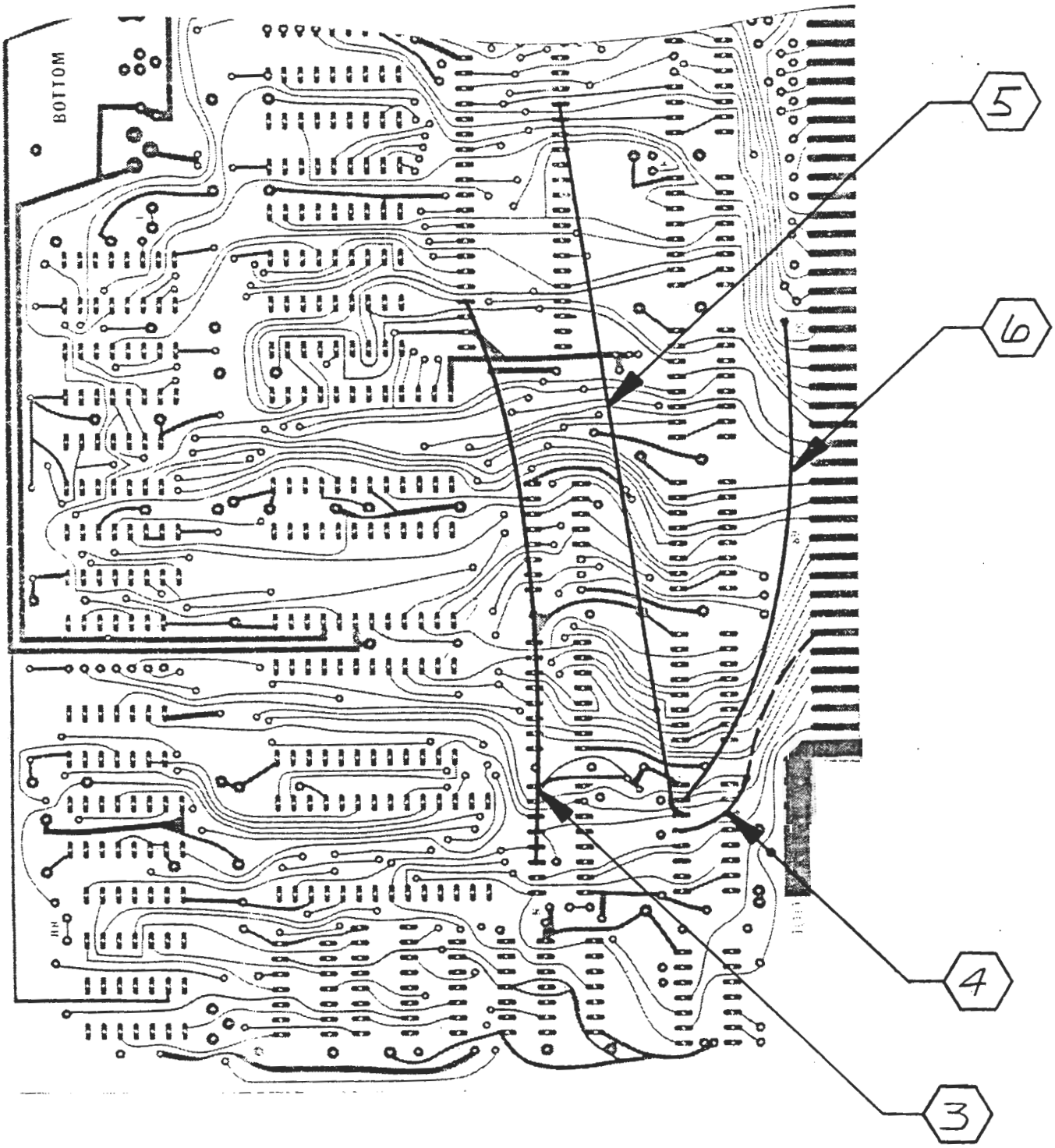

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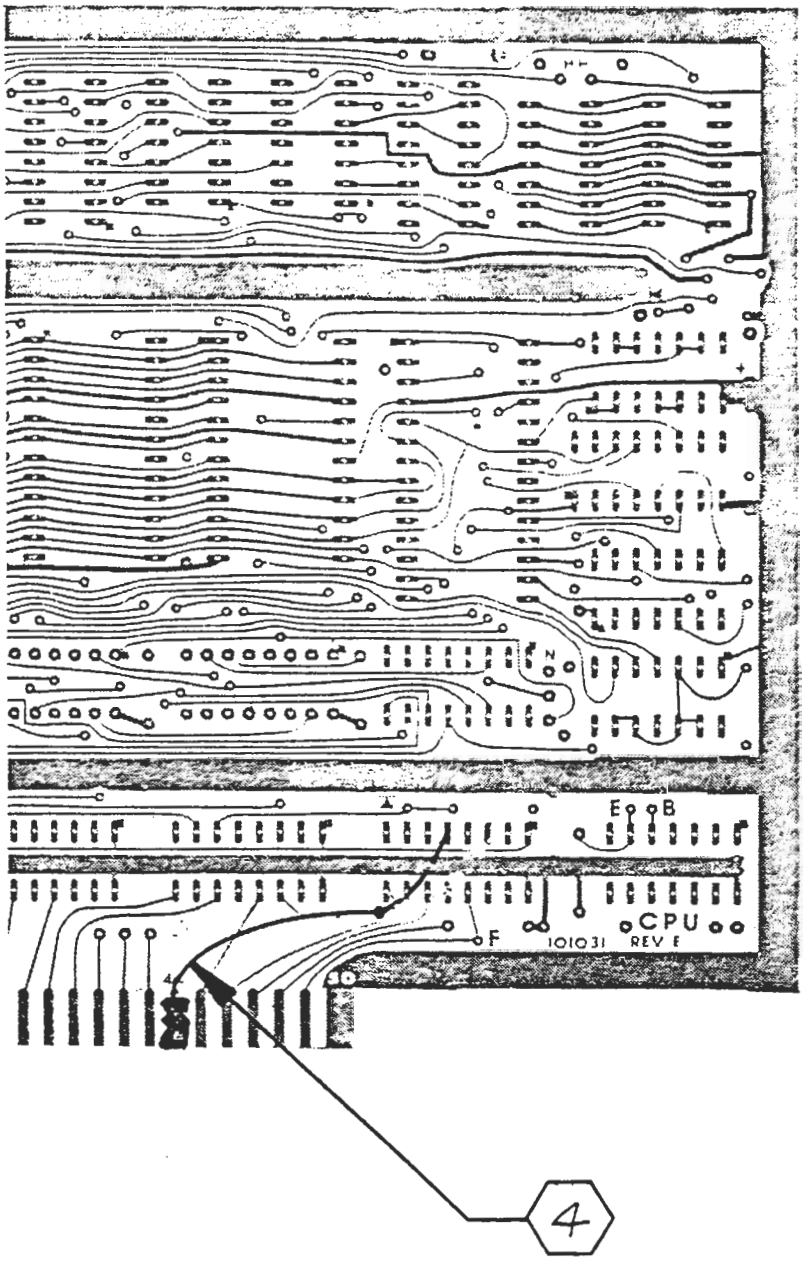

NOTE: Coat Gold Tabs with white Solder Mask or masking tape showing only the top portion of the tab as shown.